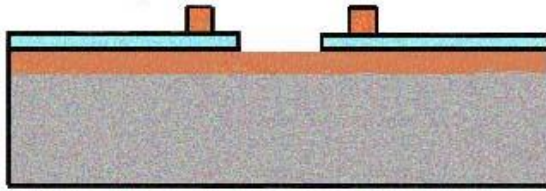


**FASTHERM® TECHNOLOGY
BASE BIMETAL Cu/Al**

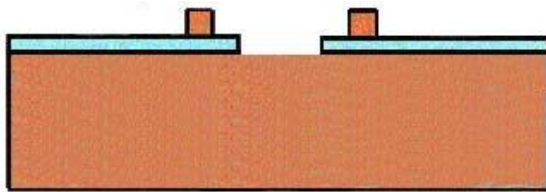


ALUMINIUM
 THERMAL PREPREG
 COPPER

**Thickness Base Material: Al 0.93 - 1.43mm
Cu 100µm**

Thickness Dielectric: 25 µm
Thickness Cu: 35 - 70 - 105µm
Min drill: 1mm
Min conductor width: 0.15mm
Min conductor space: 0.15mm
Min annular ring: 0.18mm

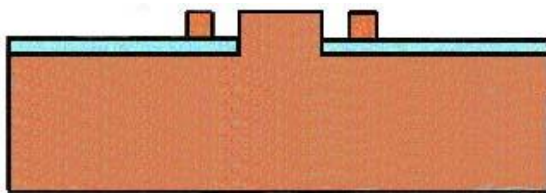
**FASTHERM® TECHNOLOGY
BASE Cu**



THERMAL PREPREG
 COPPER

Thickness Cu Base: 0.4 -1 - 1.5 - 2mm
Thickness Dielectric: 25 µm
Thickness Cu: 35 - 70 - 105 µm
Min drill: 1mm
Min conductor width: 0.15mm
Min conductor space: 0.15mm
Min annular ring: 0.18mm

**DIRECTHERM TECHNOLOGY
BASE Cu**



THERMAL PREPREG
 COPPER

Thickness Cu Base: 0.4 -1 - 1.5 - 2mm
Thickness Dielectric: 125 µm
Thickness Cu: 35 - 70 - 105 µm
Min drill: 1mm
Min Thermal pad: 0.6x1.4mm
Max Thermal pad: 5x5mm
Space Thermal pad: 1mm min
Min conductor width: 0.15mm
Min conductor space: 0.15mm
Min annular ring: 0.18mm